Tool ID: 602
Tool Location: 107

Equipment Information Sheet

FleXus Film Stress Measurement

Manager: Philip Schneider 607-254-4931
Backup: Giovanni Sartorello 607-254-4853

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- No unusual hazards during normal operation

USAGE RESTRICTIONS

- No buddy system restrictions imposed on normal operation

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 15 minutes

- Maximum 6 hour block reservations anytime
- Maximum 12 hours reserved in advance at any time per person
- No consecutive research group reservations
- Users/Groups may use any amount of unreserved time
- Additional individual restrictions may be imposed

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- Whole wafers only
- Wafer top surface must reflect a laser beam, without too much scatter.
- Wafer/substrate material must be included in the Flexus software list of material data.

Last Updated: 03/26/2025